



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ060NE2LS		<b>Issued</b>		14. August 2015	
<b>MA#</b>				MA001015336					
<b>Package</b>				PG-TSDSON-8-25		<b>Weight*</b>		35.30 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.182	0.52	0.52	5156	5156	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		70		
	non noble metal	zinc	7440-66-6	0.010	0.03		279		
	non noble metal	iron	7439-89-6	0.197	0.56		5574		
wire	non noble metal	copper	7440-50-8	7.988	22.63	23.23	226334	232257	
	noble metal	gold	7440-57-5	0.030	0.09	0.09	856	856	
encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1087		
	plastics	epoxy resin	-	1.977	5.60		56004		
	inorganic material	silicondioxide	60676-86-0	17.176	48.66	54.37	486634	543725	
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11339	11339	
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	576	576	
solder	noble metal	silver	7440-22-4	0.008	0.02		228		
	non noble metal	tin	7440-31-5	0.006	0.02		182		
	non noble metal	lead	7439-92-1	0.307	0.87	0.91	8701	9111	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33		
	non noble metal	zinc	7440-66-6	0.005	0.01		133		
	non noble metal	iron	7439-89-6	0.094	0.27		2663		
	non noble metal	copper	7440-50-8	3.816	10.81	11.09	108116	110945	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
	non noble metal	iron	7439-89-6	0.073	0.21		2065		
	non noble metal	copper	7440-50-8	2.959	8.38	8.60	83841	86035	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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